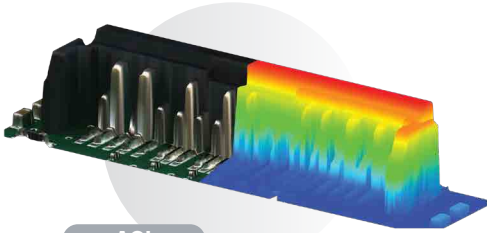


SQ3000™ 3D AOI, SPI, & CMM

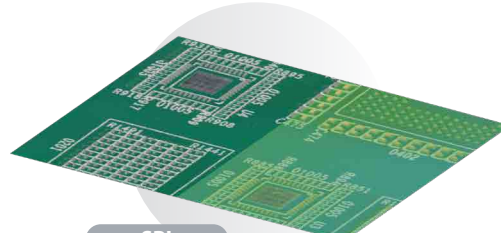
The Ultimate in Speed and Accuracy with Multi-Process Capability.

SQ3000™

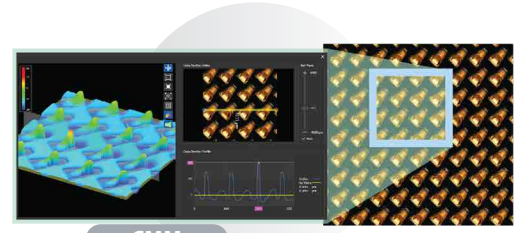
- SQ3000™ is an all-in-one solution that's loaded with powerful tools that cover inspection and measurement for AOI, SPI and CMM applications.
- The SQ3000™ offers unmatched accuracy with the revolutionary Multi-Reflection Suppression (MRS) technology by meticulously identifying and rejecting reflections caused by shiny components. Effective suppression of multiple reflections is critical for accurate measurement, making MRS an ideal technology solution for a wide range of applications including those with very high quality requirements.



AOI



SPI



CMM

Metrology-Grade Accuracy at Production Speed

- Achieve metrology-grade accuracy at production speed enabled by MRS technology.
- Attain repeatable and reproducible measurements for Industrial Metrology, Semiconductor, Microelectronics and SMT applications.

Faster, Smarter, Award Winning Software

- Simplifies process with powerful yet extremely simple software designed with an intuitive interface that reduces training efforts and minimizes operator interaction.
- Take ease-of-use to a whole new level of inspection with multi touch controls and 3D image visualization tools with CyberOptics 3D AOI software that includes full SPI capability, and expanded coordinate measuring capabilities with CyberCMM™.
- Add on CyberReport™ for full-fledged machine-level to factory-level SPC capability.



Richer SPI Experience with Closed Loop, Feedback - Feed Forward

- Optimize printing process by proactively analyzing current trend data with the standalone SPI software and CyberPrint Optimizer.
- Enable smarter and faster inspection that provides reduction in rework costs, minimizes scrap and optimizes print process.



SMT Inspection Capabilities		MRS Sensor	Ultra High Resolution MRS Sensor
Inspection Speed	50 cm ² /sec (2D+3D)		15 cm ² /sec (2D+3D)
Minimum Component Size	0402 mm (01005 in.)		0201 mm (008004 in.)
PCB Size	SQ3000: 510 x 510 mm (20 x 20 in.), SQ3000-X: 710 x 610 mm (27.9 x 24 in.)		
Component Height Clearance	50 mm		
PCB Thickness	0.3 - 5 mm		
Component Types Inspected	Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and more		
Component Defects	Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and more		
Solder Joint and Other Defects	Gold finger contamination, excess solder, insufficient solder, bridging, through-hole pins		
3D Measurement Inspection	Lifted Lead, package coplanarity, polarity dimple and chamfer identification		
Solder Paste Inspection	Height, area, volume, registration and bridge detection		
Measurement Gage R&R	<10% @ ±3σ		
Z Height Accuracy	1 μm on certification target		
Z Height Measurement Range	6 mm at spec, 24 mm capability		3 mm at spec, 10 mm capability
CMM Capabilities			
Accuracy XY / Z	3 μm / 2 μm		2 μm / 2 μm
Resolution XY / Z	10 μm / 1 μm		7 μm / 1 μm
Maximum Weight	SQ3000: 3 kg (5 kg Option), SQ3000-X: 10 kg		
Min./ Max. Feature Height	Min. 2 μm ; Max. 24mm		Min. 2 μm ; Max. 10mm
Maximum Feature Size	SQ3000: 510 x 510 mm (20 x 20 in.), SQ3000-X: 710 x 610 mm (27.9 x 24 in.)		
Carrier Thickness	0.3 - 5 mm (10 mm Option)		
Coordinate Measurement Capability	Line / Distance / X,Y / Mid Line, Inter Point / Regression Shifted, Datum X,Y / LSF X,Y Offset, X,Y Offset / Value / Location / List of X,Y Values, Height / Local Height / Regression / Radius, Coplanarity/ Distance to plane / 2nd Order fitting, Difference / Absolute / 2sqrt / VC, Max / Min / Ave / Sigma / Plus / Minus / Multiple		
Vision System & Technology			
Imagers	Multi-3D sensors		
Resolution	Sub 10 μm		7 μm
Image Processing	Autonomous Image Interpretation (AI ²) Technology, Coplanarity and Lead Measurement		
Programming Time	<15 minutes (for established libraries)		
CAD Import	Any column-separated text file with ref designator, XY, Angle, Part no info; Valor process preparation		
System Specifications			
Machine Interface	SMEGA, RS232 and Ethernet		
Power Requirements	100-120 VAC or 220-240 VAC, 50/60 hz, 10 amp max.		
System Dimensions	110 x 127 x 139 cm (W x D x H)		
Weight	≈965 kg (2127 lbs.)		
Options			
Barcode Reader, Rework station, SPC Software, Alignment Target., Programming Software: ePM-SPI/AOI & GC-PowerPlace, Offline Defect Review. SQ3000-X (Large Board Capability), SQ3000-D (Dual Lane), and SQ3000-DD (Dual Lane - Dual Sensor) models available			



Contact CyberOptics today for more information

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